

REMARKS

Rejections Under 35 USC §103(a)

These rejections are from the final Office Action mailed 09/12/2005.

Claims 1-20 and 42-44 stand rejected under 35 USC §103(a) over Krall (US Patent No. 4,713,235) in view of Chorbadjiev et al. (article entitled "The effect of fillers upon properties of electroconductive cyanoacrylate adhesives from the International Journal of Adhesion and Adhesives July 1988), the admitted prior art, either one of Zwick (US Patent No. 5,690,766) or PCT WO 97/06953, and either one of Loctite 410 or Loctite 416, optionally further taken with the state of the prior art as exemplified by at least one of Liang et al. (US Patent No. 5,233,131), Fogal et al. (US Patent No. 5,140,404), Farnworth (US Patent No. 5,218,229), Davis (US Patent No. 5,214,307) and German Patent 4107347.

Claims 21, 22, 40 and 41 stand rejected under 35 USC §103(a) over the admitted prior art in view of either one of PCT WO/06953 or Zwick (US Patent No. 5,690,766) and further taken with JP 58-196280.

The references and rejections were previously discussed in the Amended Appeal Brief dated January 30, 2006, in the Examiner's Answer mailed March 2, 2006, and in the Decision On Appeal decided February 8, 2007.

In response to the rejections under 35 USC §103(a), each of the independent claims has been amended to include additional limitations which further distinguish the claimed method from the prior art. Specifically, independent claims 1, 6, 12, 15, 21, and 42 each state that the "polymerizing" step is performed "between the temperature of 20 °C to 30 °C and at the ambient atmosphere, without heating the die and the leadframe, without adding to a thermal budget of the die, and without introducing thermal stresses in the die".

Antecedent basis for the "temperature of 20 °C to 30 °C and at the ambient atmosphere" recitation, is contained on page 10, lines 11-13 of the specification.

Antecedent basis for the "without heating the die and the leadframe" recitation is contained on page 10, lines 13-15 of the specification.

Antecedent basis for the "without adding to a thermal budget of the die" recitation is contained on page 3, lines 24-27 of the specification.

Antecedent basis for the "without introducing thermal stresses" recitation is contained on page 3, lines 33-35 of the specification.

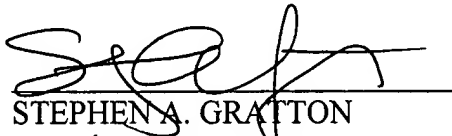
The additional recitations are submitted to distinguish the method from the art because the references in combination do not disclose or suggest a "polymerizing" step performed with the stated parameters. In addition, the claimed method provides new and improved results in that semiconductor components packaged using the method have a low thermal budget and no thermal stresses introduced by the packaging process.

Conclusion

In view of the amendments and arguments, favorable consideration and allowance of claims 1-22, and 40-44 is requested. Should any issues remain, the Examiner is asked to contact the undersigned by telephone.

DATED this 6th day of April, 2007.

Respectfully submitted:



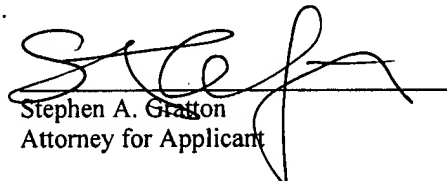
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04/06/2007
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